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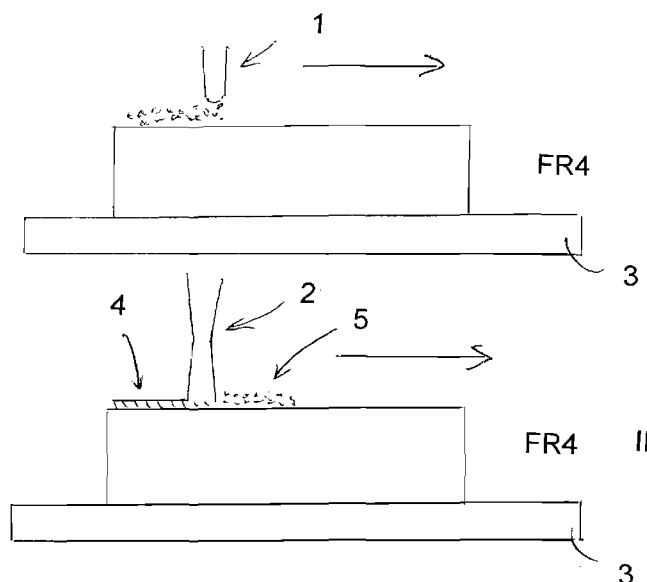


FIG. 2

(57) Abstract: Method for connecting the conductive surfaces of circuit boards, especially a circuit board equipped with at least two conductive surfaces separated by an insulator layer and with holes, or for creating conductors on a board in a manner that conducts electricity. In the method, a metal or metal alloy, in a powder form, is fed into and the powder is sintered using a laser in order to create a unified conductive structure.

WO 2008/152193 A1